

Automotive power Schottky rectifier

Datasheet – production data

Features

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Low thermal resistance
- Extremely fast switching
- Surface mounted device
- Avalanche capability specified
- AEC-Q101 qualified

Description

This single chip Schottky rectifier is suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in SMB, and SMC, this device is intended for use in low and medium voltage operation, high frequency inverters, free wheeling and polarity protection applications where low switching losses are required for automotive applications.

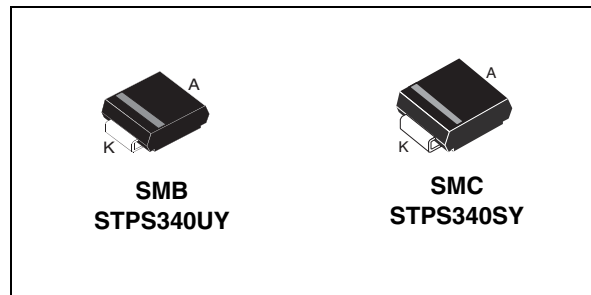


Table 1. Device summary

$I_{F(AV)}$	3 A
V_{RRM}	40 V
T_j (max)	150 °C
V_F (max)	0.57 V

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit	
V _{RRM}	Repetitive peak reverse voltage		40	V	
I _{F(RMS)}	Forward rms current		6	A	
I _{F(AV)}	Average forward current	SMB	T _L = 95 °C δ = 0.5	3	A
		SMC	T _L = 105 °C δ = 0.5	3	A
I _{FSM}	Surge non repetitive forward current		t _p = 10 ms sinusoidal	75	A
P _{ARM}	Repetitive peak avalanche power		t _p = 1 μs T _j = 25 °C	1300	W
T _{stg}	Storage temperature range		-65 to + 150	°C	
T _j	Operating junction temperature ⁽¹⁾ range		-40 to +150	°C	

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
R _{th(j-l)}	Junction to lead	SMB	25	°C/W
		SMC	20	

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}			20	μA
		T _j = 125 °C			2	10	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 25 °C	I _F = 3 A			0.63	V
		T _j = 125 °C			0.52	0.57	
		T _j = 25 °C	I _F = 6 A			0.84	
		T _j = 125 °C			0.63	0.72	

1. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.050 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current (per diode)

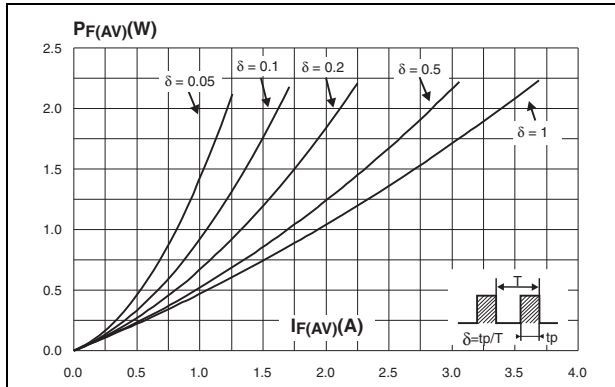


Figure 2. Average forward current versus ambient temperature (delta = 0.5, per diode)

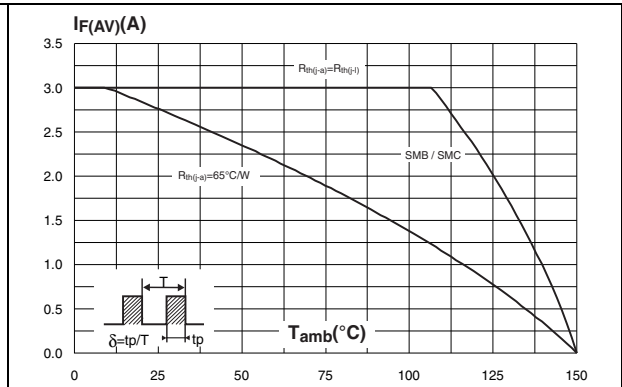


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values) (SMB)

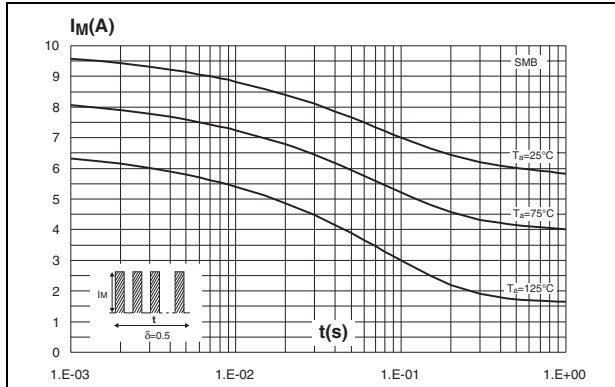


Figure 4. Non repetitive surge peak forward current versus overload duration (maximum values) (SMC)

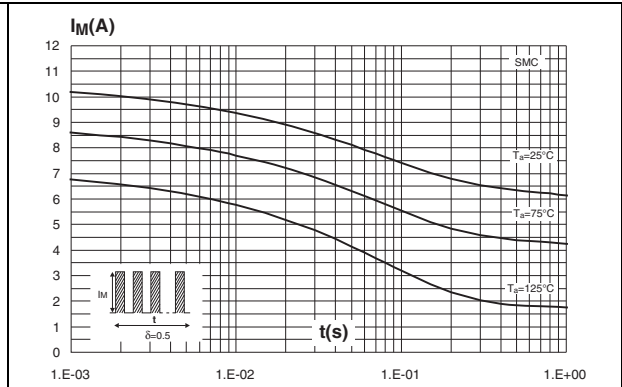


Figure 5. Normalized avalanche power derating versus pulse duration

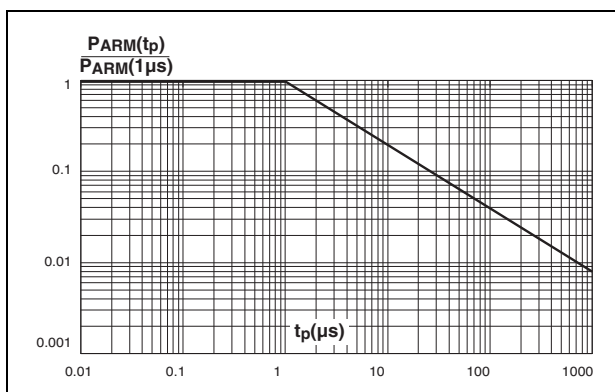


Figure 6. Normalized avalanche power derating versus junction temperature

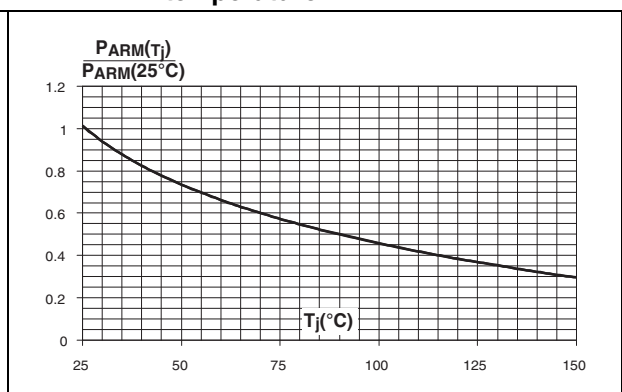


Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)

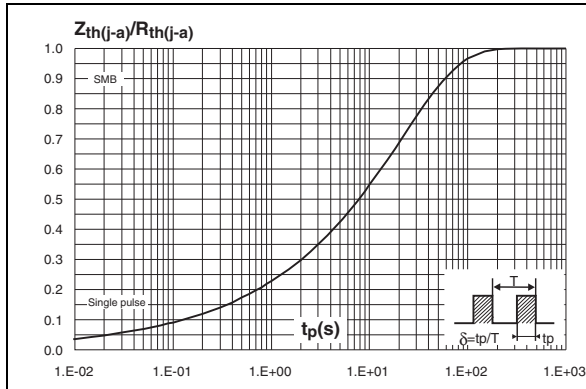


Figure 8. Relative variation of thermal impedance junction to ambient versus pulse duration (SMC)

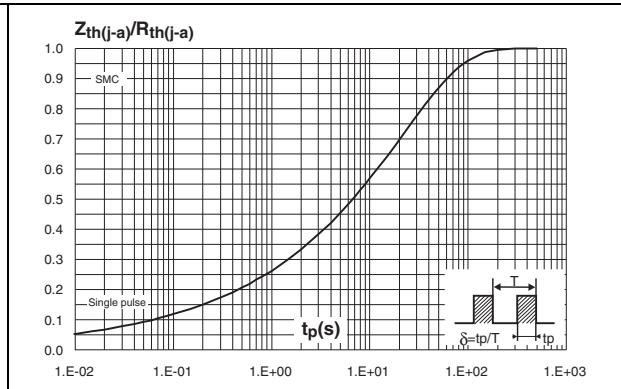


Figure 9. Reverse leakage current versus reverse voltage applied (typical values)

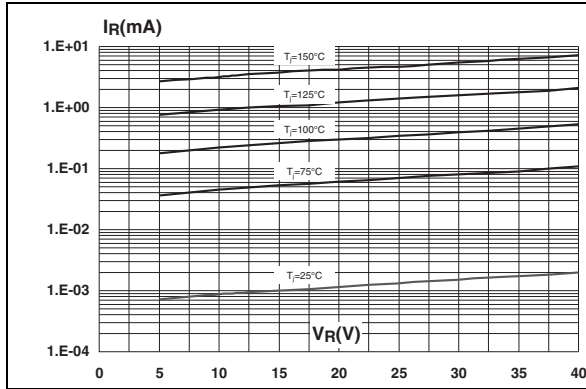


Figure 10. Junction capacitance versus reverse voltage applied (typical values)

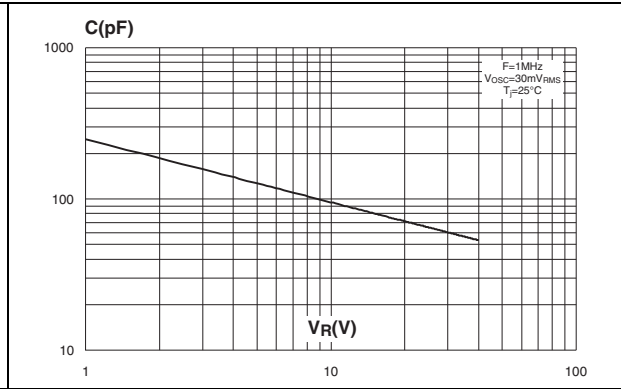


Figure 11. Forward voltage drop versus forward current

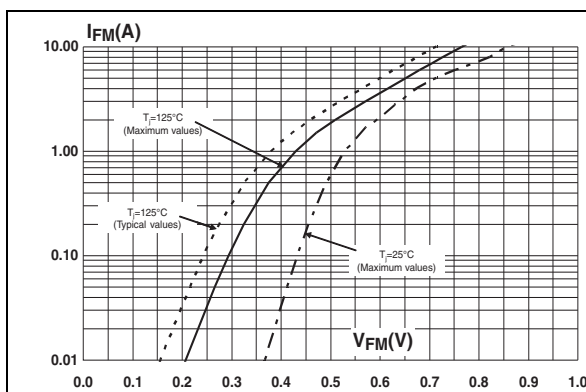
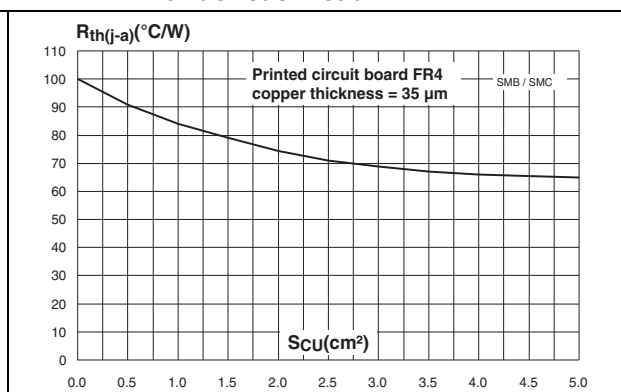


Figure 12. Thermal resistance junction to ambient versus copper surface under each lead



2 Package information

- Epoxy meets UL94, V0
- Band indicates cathode on SMB and SMC

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. SMB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.50	0.030	0.059

Figure 13. SMB footprint (dimensions in mm)

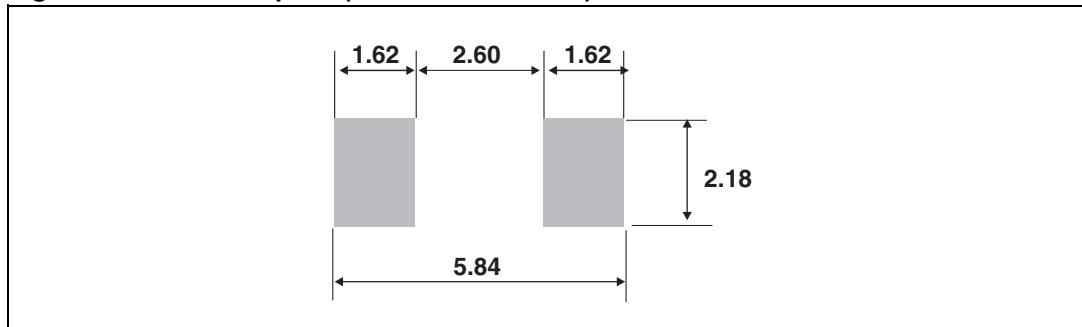
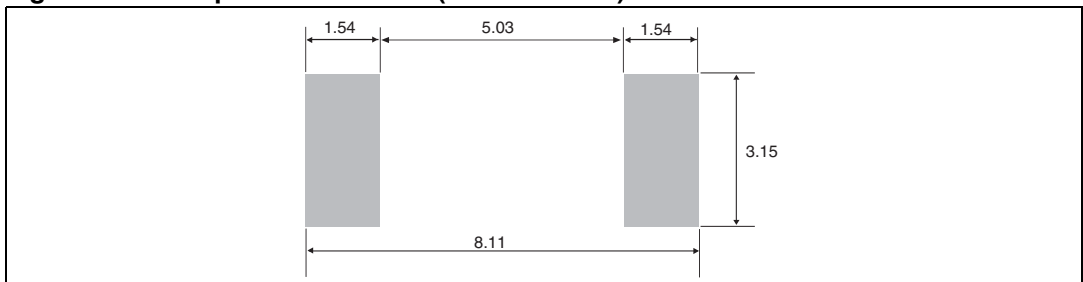


Table 6. SMC package dimensions

Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.40	0.030	0.063

Figure 14. Footprint dimensions (in millimeters)



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS340UY	U34Y	SMB	0.107 g	2500	Tape and reel
STPS340SY	S34Y	SMC	0.243 g		

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
24-Oct-2012	1	First issue.

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY TWO AUTHORIZED ST REPRESENTATIVES, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2012 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9